



Product Change Notification

Change Notification #: 114762 - 00
Change Title: Intel® Server Chassis H2312XXKR2
PCN 114762 – 00
Product Material, Front panel bezel change
Date of Publication: July 8, 2016

Key Characteristics of the Change:

Product Material, Change to front panel bezel

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	July 11, 2016
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Description of Change to the Customer:

Intel is implementing the following change on the Intel® Server Chassis H2312XXKR2:

1. Change the housing mini-FP bezel material from plastic to die-cast to align with the Intel® Server Chassis H2224XXKR2 mini-FP bezel.

Figure 1. mini-FP bezel (Left and Right) post-change



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
H2312XXKR2	933689	H20865-006	H20865-007

PCN Revision History:**Date of Revision:**

July 8, 2016

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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